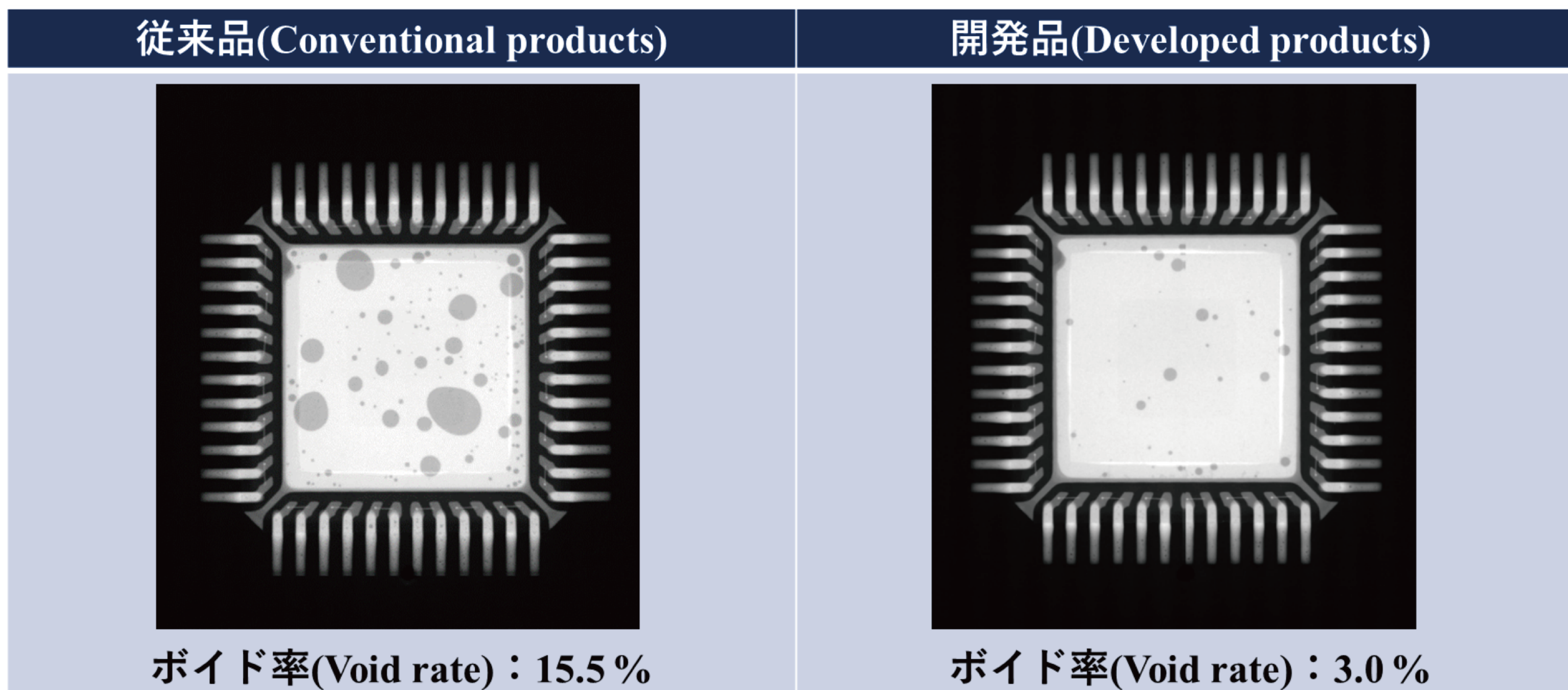
車載、高信頼性製品に対応！超低ボイドはんだペースト！

Ultra-low void solder paste for automotive and high reliability products

NP303-VLP102-T4

フラックス開発で大幅なボイド抑制実現

Flux development achieves significant void suppression.

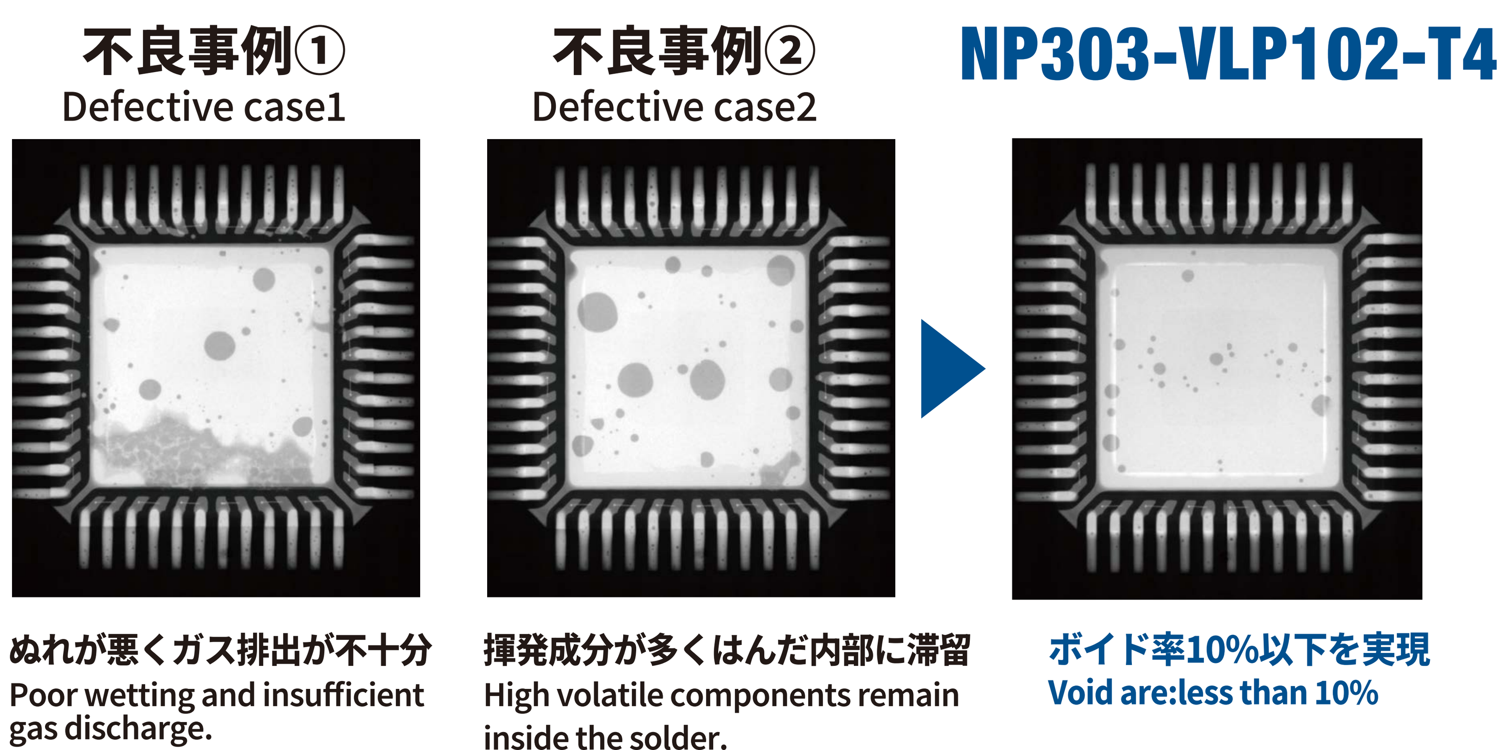


ボイド低減へのフラックス設計

Flux design for void reduction

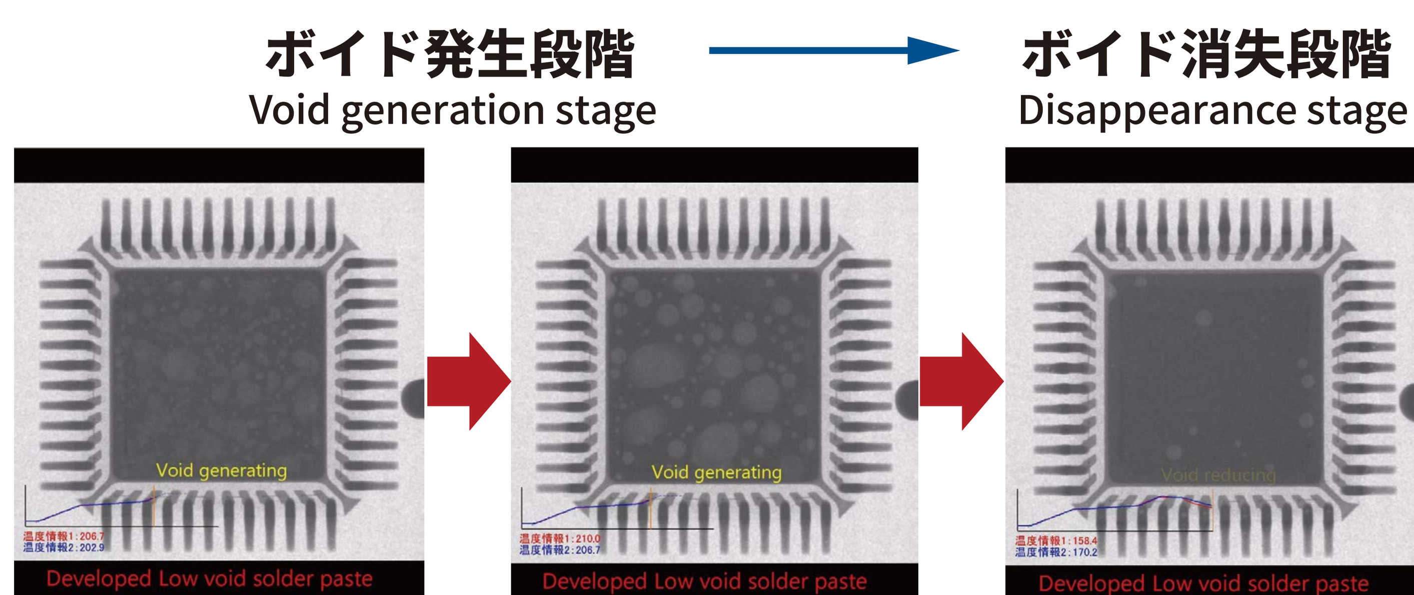
- **高い濡れ性により、溶融時のはんだ内部のガス排出を促進**
  Excellent wettability facilitates gas emissions from the flux of solder paste during melting.

- **ガスが発生しやすい成分を低減**
  Reduce ingredient prone to occurrence of gas.



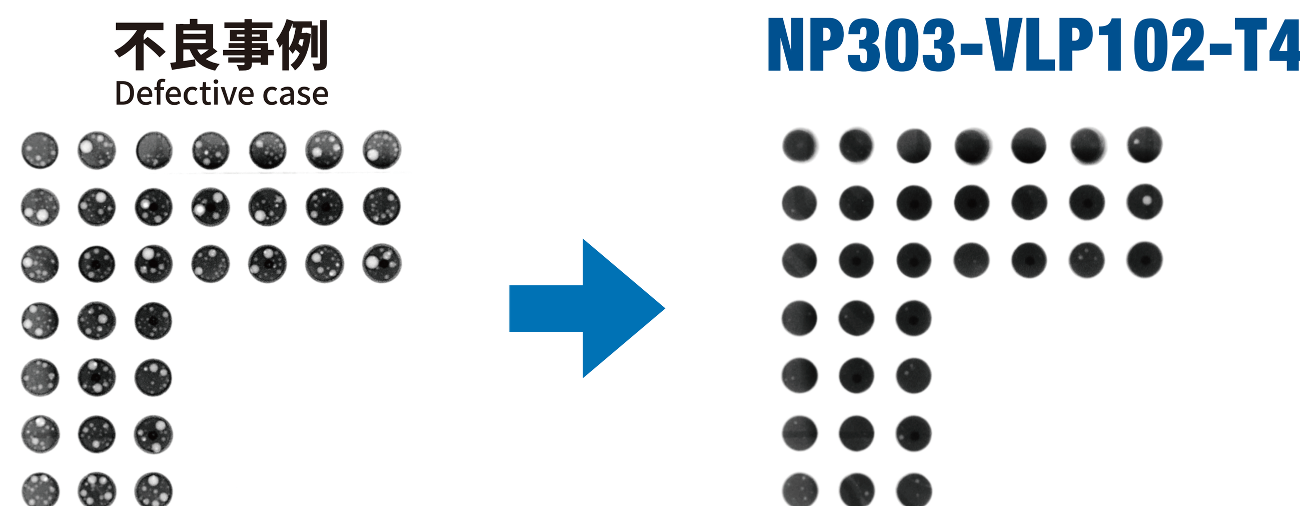
加熱時のボイド発生挙動

Voiding behaviour during heating



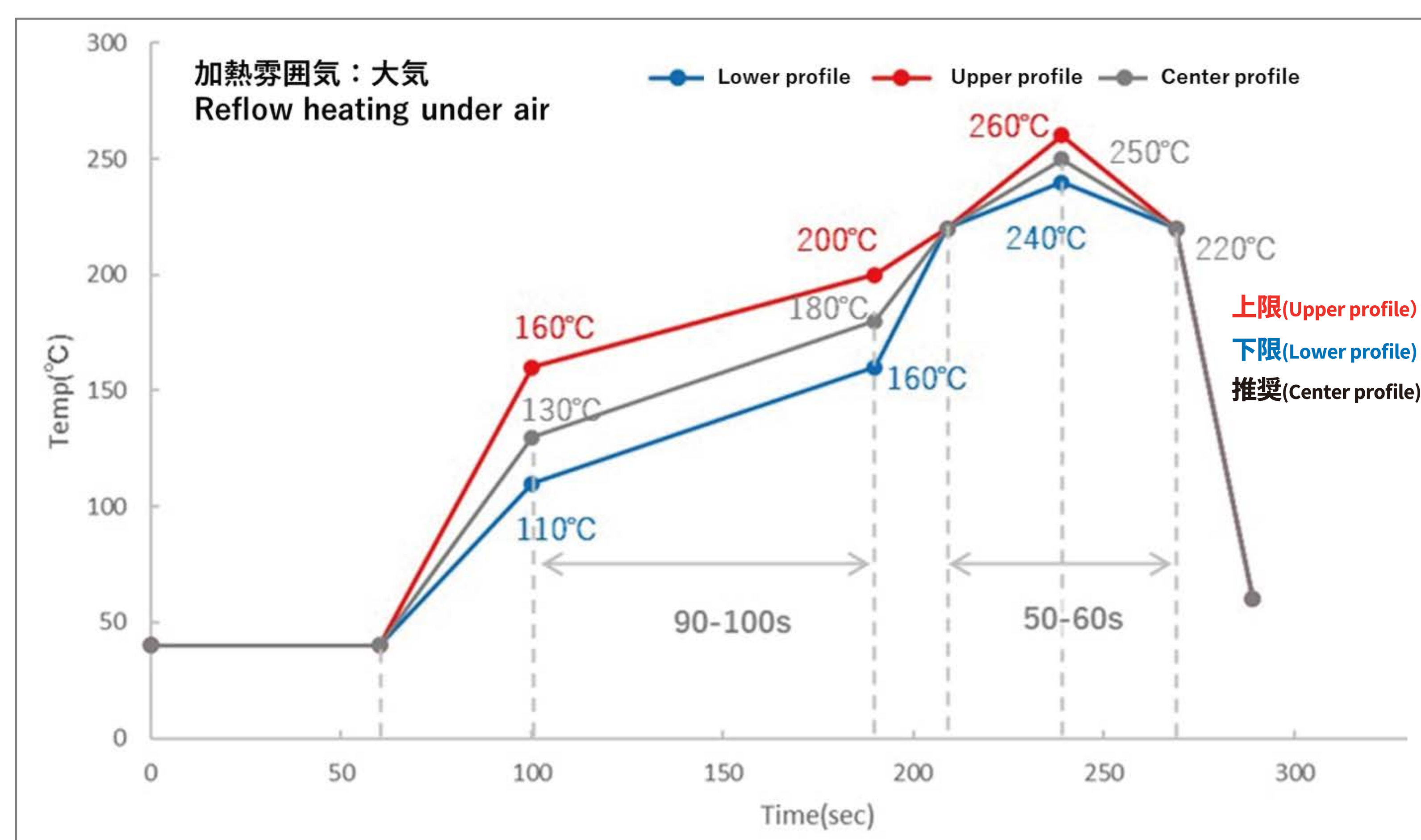
BGA部品への適用

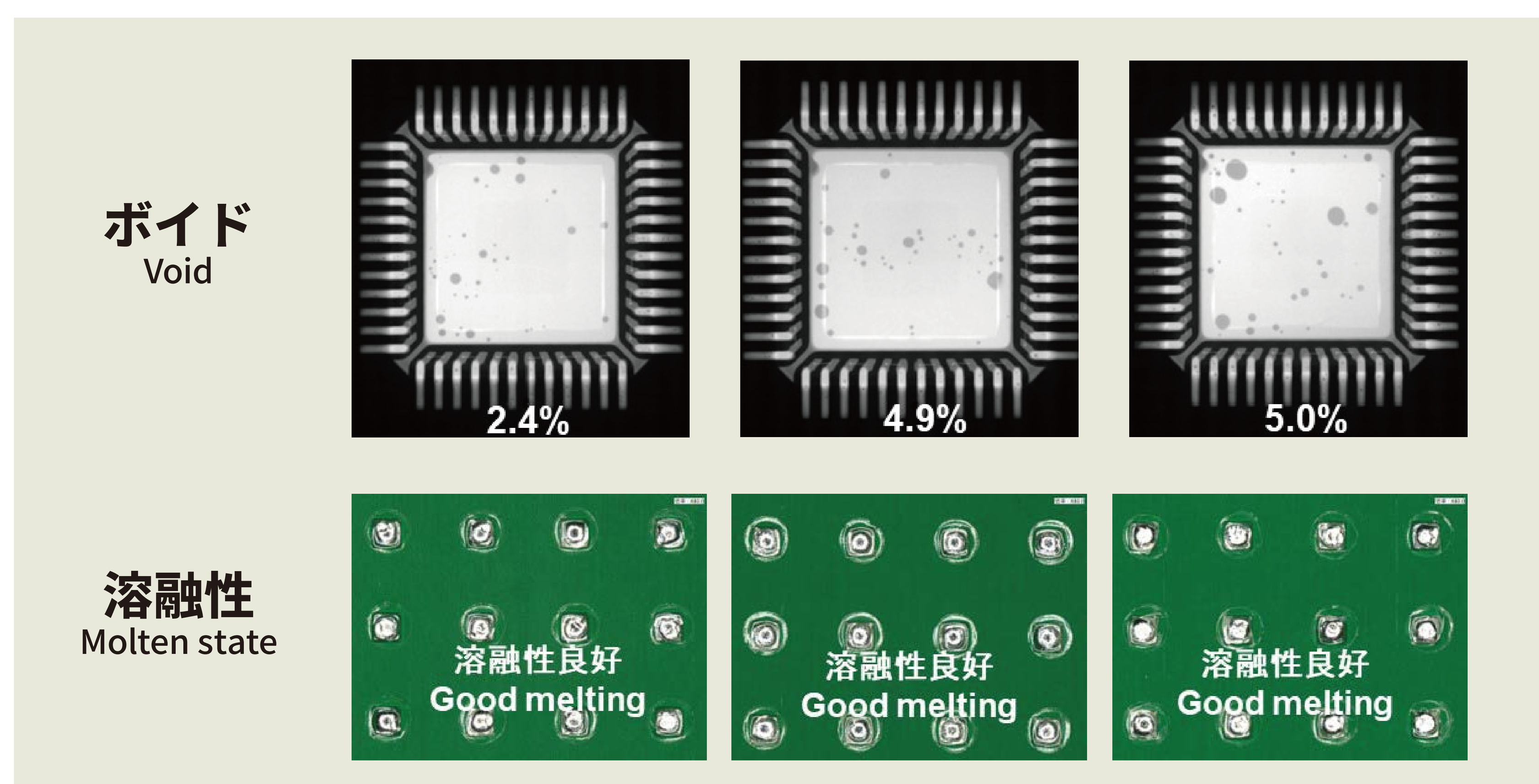
Applied for Ball Grid Array components



リフロープロファイルの制約を受けません

Not constrained by reflow profiles





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